



Highlights

- Electronics-grade pure silica-based nanoparticles, designed for silicon wafer stock polishing
- Broad particle size distribution provides unique balance of rate and finish
- Engineered products stable across a broad pH range

Colloidal silica slurries

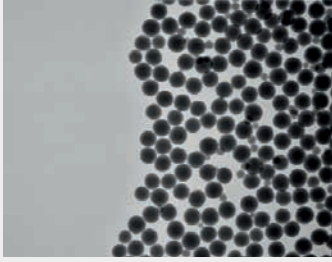
NALCO™

NALCO™ colloidal silica polishing slurries are designed to lower the residual metal levels on wafers after the stock polishing process. The chemical additive package specifically targets copper ions to prevent their transfer into the bulk of the wafer. They feature a proprietary blend of three custom particle sizes, high concentration, and a low cost of ownership. This is especially effective on silicon surfaces due to temperature-sensitive amine which activates at 40 degrees Celsius.

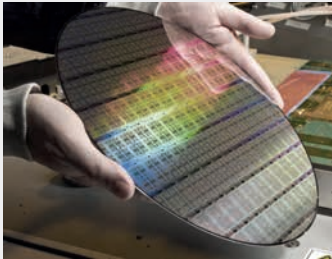
Typical applications

Silicon

Order code	Base material	Particle size [µm]	pH value	Solids content [%]
NALCO™ 2329	Colloidal silica	0,08	8,4	40,0
NALCO™ 2350	Colloidal silica	0,06	11,0	50,0
NALCO™ 2358	Colloidal silica	0,07	12,0	28,0
NALCO™ 2360	Colloidal silica	0,06	8,5	50,0
NALCO™ 2371	Colloidal silica	0,07	11,8	28,0
NALCO™ 2398	Colloidal silica	0,09	11,8	28,0
NALCO™ 2398LMS	Colloidal silica	0,09	11,8	28,0



NALCO™ polishing slurries are an excellent colloidal silica designed for stock removal processes.



NALCO™ colloidal silica polishing slurries are most commonly used to polish, prime, and reclaim silicon wafers.



Pureon offers a wide range of customized solutions. Get in touch with us.

Product specifications

Base material Colloidal silica
Shelf life 24 months

Order information

Packing 5 gal jugs, and 55 gal drums.
264 gal tote, and 330 gal tote.
Other sizes available upon request.
Unit of measure Gallon [gal]

Application recommendations

Handling Storage tanks and distribution piping should be constructed of engineering plastic, such as polyethylene, polypropylene, or PTFE. Materials such as aluminum, copper, brass, and PVC should be avoided. Avoid leaving slurry containers open for extended periods of time. Leaving containers open may result in drying which can cause wafer scratching.

Storage Storage outside of the recommended conditions may result in irreversible product degradation. Products can be stored up to the expiration date between the temperatures range of 0 °C – 45 °C (32 °F – 113 °F). Avoid prolonged exposure at temperatures at either extreme. In all cases, the products should be allowed to return to a room temperature prior to use. All shipments include temperature indicators to monitor shipping conditions.

Disposal Dispose of in accordance with all applicable local regulations.

Pureon is an authorized distributor of NALCO™.

Contact

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